

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.71672	100.0	7.7
			<b>Subtotal</b>	<b>0.71672</b>	<b>100</b>	<b>7.7</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03733	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.0112	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03733	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.23966	99.77	400.0777
			<b>Subtotal</b>	<b>37.32552</b>	<b>100</b>	<b>401</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.82818	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.89203	10.0	63.3
	Filler	Silica fused	60676-86-0	50.08228	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11784	0.2	1.266
			<b>Subtotal</b>	<b>58.92033</b>	<b>100</b>	<b>633</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.32703	100.0	25
			<b>Subtotal</b>	<b>2.32703</b>	<b>100</b>	<b>25</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01789	100.0	0.19218
	Pure metal	Aluminium (Al)	7429-90-5	0.30158	100.0	3.24
			<b>Subtotal</b>	<b>0.31947</b>	<b>200</b>	<b>3.43218</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00782	2.0	0.084
	Lead alloy	Silver (Ag)	7440-22-4	0.00977	2.5	0.105
	Lead alloy	Lead (Pb)	7439-92-1	0.37335	95.5	4.011
			<b>Subtotal</b>	<b>0.39094</b>	<b>100</b>	<b>4.2</b>
			<b>Total</b>	<b>100.00001</b>	<b>100</b>	<b>1074.33218</b>

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